

PMP4447 BOM List

Item	Qty	Reference	Part Name	MFR	Value	Package	Description
1	1	C7	Std	std	0.1uF, 50v	603	Capacitor, Ceramic, 10%
2	1	C8	Std	Std	1000pF, 100V	603	Capacitor, Ceramic, 5%
3	1	C3	GRM31A7U2J221JW31D	Murata	220pF, 630V	1206	Capacitor, Ceramic, 5%
4	1	C4	C2012X5R1E106K	TDK	10uF, 25V	805	Capacitor, Ceramic, 10%
5	1	C9	NA		NA	1206	Capacitor, Ceramic, 10%
6	1	C10	Std	Std	470pF, Y CAP	TH type	Y capacitor
7	1	D1	MB6S	FSC/others	0.5A/600V	SOIC4	Bridge Rectifier, 600V, 0.5A
8	1	D4	MBRS3100	ON	3A, 100V	SMC	Diode, Schottky, 3A, 100V
9	1	D2	BAS21HT1G	ON	0.2A, 200V	SOD323	Switching diode, 0.2A, 200V, SOD323
10	1	D3	DFLR1600	Diodes	1A, 600V	POWERDI123	Standard rectifier, 1A, 600V, POWERDI123
11	1	FB1	MPZ2012S601A	TDK		805	Ferrite bead
12	1	FR	20T-010H	Holly	1A, 250V	R1/4WA	Micro fuse(resistor type fuse), 1A, 250V
13	1	L1	7447462471	Wurth	470uH	TH type	5mm*8mm bobbin
14	1	T1	750841034	Wurth		TH type	EE16-10pin
15	1	R5	Std	Std	1k	603	Resistor, Chip, 1/8W, 1%
16	1	R4	Std	Std	2.2	603	Resistor, Chip, 1/8W, 1%
17	1	R6	Std	Std	43k	603	Resistor, Chip, 1/8W, 1%
18	1	R8	Std	Std	82k	805	Resistor, Chip, 1/5W, 1%
19	1	R7	Std	Std	620k	603	Resistor, Chip, 1/8W, 1%
20	2	R11-12	Std	Std	NA	603	Resistor, Chip, 1/8W, 1%
21	1	R9	Std	Std	22	805	Resistor, Chip, 1/5W, 1%
22	1	R2	Std	Std	300R	1206	Resistor, Chip, 1/4W, 1%
23	1	R1	Std	Std	300k	1206	Resistor, Chip, 1/4W, 1%
24	1	R10	Std	Std	NA	603	Resistor, Chip, 1/8W, 1%
25	2	C1-2	KSH685M400S1A5H1CK	TEAPO	6.8uF, 400V	8mm (D) x12.5mm (H)	size, 8mmx12.5mm
26	2	C5-6	SJ series	TEAPO	330uF, 16V	8mm (D) x11mm (H)	size, 8mmx11mm
27	1	U1	UCC28910	TI		S08	
28	1	J1	USB-A	std		TH type	USB connector, Type a, Receptacle, Up right, /Vertical single
29	2	J2, J3				TH type	3mm jumper

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